

04/03/2017

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MODEL: HSS-B20-05H **DESCRIPTION: HEAT SINK**

FEATURES

- TO-220 package
- round hole component attachment
- solder pins for secure PCB mounting
- black anodized finish





thermal resistance¹ power dissipation¹ @ 1 W, 400 LFM @ 75°C ∆T, @ 75°C ∆T, @ 1 W, @ 1 W, 200 LFM nat conv nat conv nat conv (°C/W) (°C/W) (°C/W) (°C/W) (W) HSS-B20-05H 7.65 9.28 2.01 1.71 9.80

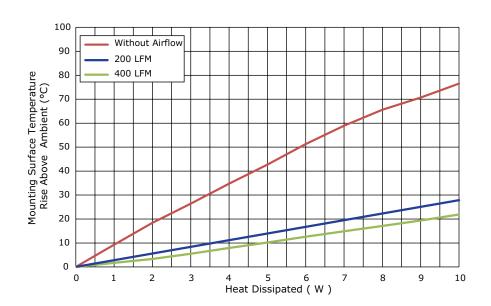
1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient ($\Delta T = Ths - Ta$) (°C)			
Power (W)	Natural Conv.	200 LFM	400 LFM	
0	0	0	0	
1	9.28	2.01	1.71	
2	18.40	4.86	3.36	
3	26.40	7.67	5.49	
4	34.76	10.40	7.93	
5	42.69	13.54	10.18	
6	51.31	16.36	12.60	
7	58.97	19.19	14.87	
8	65.64	22.01	17.14	
9	70.68	24.88	19.38	
10	76.52	27.89	21.89	
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Ths: "hot spot" temperature measured on the heatsink

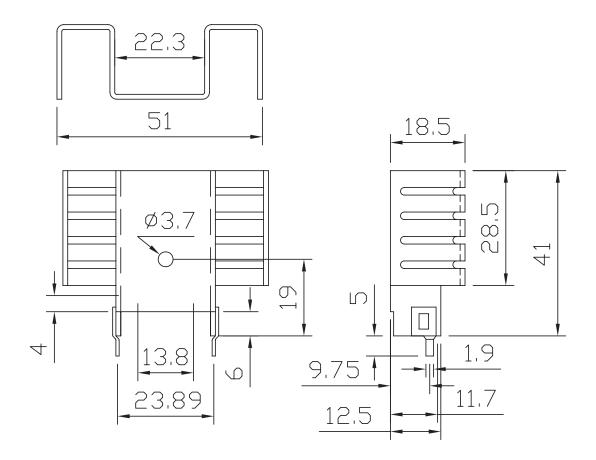
Ta: ambient temperature



MECHANICAL DRAWING

units: mm tolerance: ±0.5 mm

MATERIAL	AL1050
FINISH	black anodized
THICKNESS	1.2 mm
PIN MATERIAL	brass
PIN PLATING	tin
WEIGHT	12.0 g



REVISION HISTORY

rev.	description	date
1.0	initial release	04/03/2017

The revision history provided is for informational purposes only and is believed to be accurate.



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CUI offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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